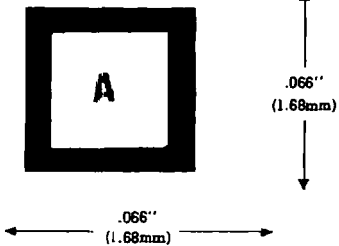


CHIP NUMBER

530



Anode: 0.042" x 0.042" (1.07mm x 1.07mm)

PN EPITAXIAL FAST RECOVERY PLANAR POWER DIODE

CONTACT METALLIZATION

Anode: > 50,000 Å Aluminum

Cathode: Gold

(Polished silicon or "Chrome Nickel Silver" also available)

Also available on:

MOLY PEDESTAL

Size: .140" Diameter (3.56mm)

Thickness: .010" (0.25mm)

BeO PEDESTAL

Size: .142" x .178" (3.61mm x 4.52mm)

Thickness: .028" (0.71mm)

ASSEMBLY RECOMMENDATIONS

It is advisable that:

- a) the chip be eutectically mounted with gold silicon preform 98/2%.
- b) 12 mil (0.305mm) aluminum wire be ultrasonically attached to the anode contact.

TYPICAL ELECTRICAL CHARACTERISTICS AT 25°C

The following typical electrical characteristics apply for a completely finished component employing the chip number 530 in a DO-4 or equivalent case:

Minimum V_R @ 10 μA	V_F @	I_F	I_F Surge	Maximum t_{rr} @ $I_F = I_R = 1.0A$ $I_{REC} = 0.25A$
> 50V	1.2V	3A	> 75A	65 ns
> 80V	1.2V	3A	> 75A	65 ns
> 100V	1.2V	3A	> 75A	65 ns
> 400V	1.8V	3A	> 30A	65 ns